PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT3178252

SUBMISSION TYPE:	CORRECTIVE ASSIGNMENT
NATURE OF CONVEYANCE:	Corrective Assignment to correct the ASSSIGNORS MIDDLE NAME FROM INITIAL TO FULL NAME previously recorded on Reel 024992 Frame 0116. Assignor(s) hereby confirms the ASSIGNMENT OF APPLICATION # 12/882,525 FROM OMAR JAMES BCHIR, MILIND PRAVIN SHAH AND SASHIDAR MOVVA TO QUALCOMM, INCORPORATED

CONVEYING PARTY DATA

Name	Execution Date
OMAR JAMES BCHIR	12/10/2014
MILIND PRAVIN SHAH	12/15/2014
SASHIDAR MOVVA	01/09/2015

RECEIVING PARTY DATA

Name:	QUALCOMM Incorporated
Street Address:	5775 Morehouse Drive
City:	San Diego
State/Country:	CALIFORNIA
Postal Code:	92121

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	12882525

CORRESPONDENCE DATA

Fax Number: (858)658-2502

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent

using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Email: us-docketing@qualcomm.com
Correspondent Name: QUALCOMM INCORPORATED
Address Line 1: 5775 MOREHOUSE DRIVE
Address Line 4: SAN DIEGO, CALIFORNIA 92121

NAME OF SUBMITTER:
LISA NODARSE

SIGNATURE:
/Lisa Nodarse/

DATE SIGNED:
01/12/2015

Total Attachments: 8

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PATENT 503131642 REEL: 034751 FRAME: 0436





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PATENT ASSIGNMENT

Electronic Version v1.1 Stylesheet Version v1.1

 SUBMISSION TYPE:
 NEW ASSIGNMENT

 NATURE OF CONVEYANCE:
 ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Omar J. Behir	09/02/2010
Miling P. Shah	09/02/2010
Sashidhar Movva	09/02/2010

RECEIVING PARTY DATA

Name:	QUALCOMM Incorporated
Street Address:	5775 Morehouse Drive
Internal Address:	Patent Department
City:	San Diego
State/Country:	CALIFORNIA
Postal Code:	92121-1714

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	12882525

CORRESPONDENCE DATA

Fax Number: (858)658-2502

Correspondence will be sent via US Mail when the fax attempt is unsuccessful.

Phone: \$58-658-5787

Email: Patent.Docketing.US@qualcomm.com

Correspondent Name: QUALCOMM Incorporated Address Line 1: 5775 Morehouse Drive Address Line 2: Patent Department

Address Line 4: San Diego, CALIFORNIA 92121-1714

ATTORNEY DOCKET

NUMBER:

100441

NAME OF SUBMITTER:

Nicholas J. Pauley

Signature:

/Nicholas J. Pauley/

Date:

09/15/2010

Total Attachments: 2

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PATENT Docket No: 100441

Page 1 of 2

ASSIGNMENT

TO WHOM IT MAY CONCERN:

For the sum of One Dollar and other valuable consideration to us in hand paid, receipt of which

is hereby acknowledged, be it known that We/I,

1. Omar James Behir, a citizen of United States, having a mailing address of 5775

Morehouse Drive, San Diego, CA 92121; and a resident of San Marcos, California.

2. Milind Fravin Shah, a citizen of India, having a mailing address of 5775 Morehouse

Drive, San Diego, CA 92121; and a resident of San Diego, California.

Sashidhar Movva, a citizen of India, having a mailing address of 5775 Morehouse Drive.

San Diego, CA 92121; and a resident of San Diego, California.

have sold, assigned and transferred and by these presents do sell, assign, transfer and set over

unto QUALCOMM Incorporated, a Delaware corporation, having a place of business at 5775

Morehouse Drive, San Diego, California 92121-1714, its successors, legal representatives, or

assigns, the entire right, title and interest in and to a certain invention relating to Process For

Improving Package Warpage and Connection Reliability Through Use of a

Backside Mold Configuration (BSMC) by me devised and the application for United States

Patent therefore filed in the United States Patent and Trademark Office on September 15, 2010,

and assigned Serial No. 12/882,525 (and I hereby authorize and instruct QUALCOMM

Incorporated to hereafter complete this Assignment by inserting the serial number and date in

the space provided above when known), including Provisional Application Number 61/346,725,

filed on May 20, 2010, and all original and reissue patents granted thereof, and all divisions,

PATENT Docket No: 100441 Page 2 of 2

ASSIGNMENT

continuations and continuations-in-part thereof, including the subject matter of any and all claims which may be obtained in every such patent, and all foreign rights to said invention, and covenant that I have full right to do so, and agree that I will communicate to said corporation or its representatives all facts known to me respecting said invention, whenever requested, and testify in any legal proceedings, sign all lawful papers, make all rightful oaths and generally do everything possible to aid said corporation, its successors, assigns and nominces, to obtain and enforce proper patent protection for said invention in all countries.

The Commissioner of Patents and Trademarks is requested to issue the Letters Patent which may be granted for said invention or any part thereof unto said corporation in keeping with this Assignment.

Done at San Diego, California this 💯	day of	<u></u>		
	Omar James Behir			
Done at San Diego, California this	day of	. 2014.		
	Milind Pravin Shah			
Done at San Diego, California this	day of			
		Sashidhar Movva		

PATENT Docket No: 100441

Page 1 of 2

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PATENT Docket No: 100441 Page 2 of 2

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Done at San Diego, California this	day of	*	, 2014.
		Omar James	Bchir
Done at San Diego, California this 15	day of <u>Dec</u>	and MC	, 2014.
		Milind Pravi	n Shah
Done at San Diego, California this	day of	-	, 2014.
		Sashidhar M	DVVa

PATENT Docket No: 100441

Page I of 2

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Done at San Diego, California this	_day of _		, 2014.	
	**********	Omar James Behir		
Done at San Diego, California this	_day of _		. 2014.	
	Milind Pravin Shah			
Done at San Diego, California this 🐴	_day of _	jan	. 2015.	
		an Saolid	<u> </u>	
			har Movva	

PATENT REEL: 034751 FRAME: 0445

RECORDED: 01/12/2015